

Sumikon® PM-TX230

Phenolic

SBHPP

Message:

SUMIKON PM-TX230 is a Heat dissipative thermoset molding compounds, Non-electrical insulative based on Phenolic polymer. It is supplied in the form of Granular/Molding Powder for Molding.

General Information			
Filler / Reinforcement	Inorganic filler		
Appearance	Black		
Forms	Powder		
	Particles		
Processing Method	Resin transfer molding		
Physical	Nominal Value	Unit	Test Method
Specific Gravity	1.83	g/cm ³	JIS K6911
Molding Shrinkage - Flow	0.16	%	JIS K6911
Mechanical	Nominal Value	Unit	Test Method
Flexural Modulus	19000	MPa	JIS K6911
Flexural Strength	95.0	MPa	JIS K6911
Impact	Nominal Value	Unit	Test Method
Charpy Notched Impact Strength	2.8	kJ/m ²	JIS K6911
Thermal	Nominal Value	Unit	
Thermal Conductivity	3.0	W/m/K	

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Recommended distributors for this material

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